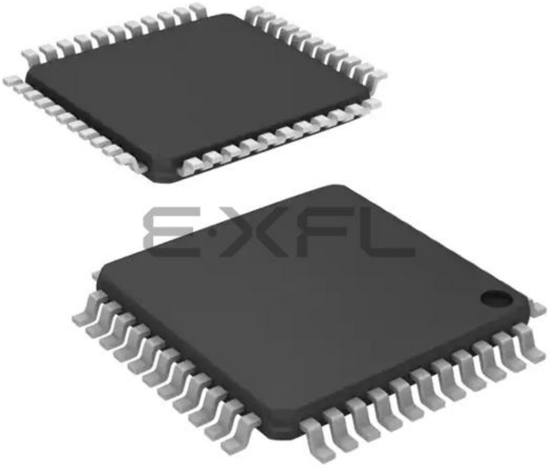


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 24x10b; D/A 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gs504-e-pt

3.5 Arithmetic Logic Unit (ALU)

The dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 ALU is 16 bits wide and is capable of addition, subtraction, bit shifts and logic operations. Unless otherwise mentioned, arithmetic operations are 2's complement in nature. Depending on the operation, the ALU can affect the values of the Carry (C), Zero (Z), Negative (N), Overflow (OV) and Digit Carry (DC) Status bits in the SR register. The C and DC Status bits operate as $\overline{\text{Borrow}}$ and $\overline{\text{Digit Borrow}}$ bits, respectively, for subtraction operations.

The ALU can perform 8-bit or 16-bit operations, depending on the mode of the instruction that is used. Data for the ALU operation can come from the W register array or data memory, depending on the addressing mode of the instruction. Likewise, output data from the ALU can be written to the W register array or a data memory location.

Refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157) for information on the SR bits affected by each instruction.

The dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 CPU incorporates hardware support for both multiplication and division. This includes a dedicated hardware multiplier and support hardware for 16-bit-divisor division.

3.5.1 MULTIPLIER

Using the high-speed, 17-bit x 17-bit multiplier of the DSP engine, the ALU supports unsigned, signed or mixed sign operation in several MCU multiplication modes:

- 16-bit x 16-bit signed
- 16-bit x 16-bit unsigned
- 16-bit signed x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit unsigned
- 16-bit unsigned x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit signed
- 8-bit unsigned x 8-bit unsigned

3.5.2 DIVIDER

The divide block supports 32-bit/16-bit and 16-bit/16-bit signed and unsigned integer divide operations with the following data sizes:

- 32-bit signed/16-bit signed divide
- 32-bit unsigned/16-bit unsigned divide
- 16-bit signed/16-bit signed divide
- 16-bit unsigned/16-bit unsigned divide

The quotient for all divide instructions ends up in W0 and the remainder in W1. The 16-bit signed and unsigned `DIV` instructions can specify any W register for both the 16-bit divisor (Wn) and any W register (aligned) pair (W(m + 1):Wm) for the 32-bit dividend. The divide algorithm takes one cycle per bit of divisor, so both 32-bit/16-bit and 16-bit/16-bit instructions take the same number of cycles to execute.

3.6 DSP Engine

The DSP engine consists of a high-speed, 17-bit x 17-bit multiplier, a barrel shifter and a 40-bit adder/subtracter (with two target accumulators, round and saturation logic).

The dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 is a single-cycle instruction flow architecture; therefore, concurrent operation of the DSP engine with MCU instruction flow is not possible. However, some MCU ALU and DSP engine resources can be used concurrently by the same instruction (for example, `ED`, `EDAC`).

The DSP engine can also perform inherent accumulator-to-accumulator operations that require no additional data. These instructions are `ADD`, `SUB` and `NEG`.

The DSP engine has options selected through bits in the CPU Core Control register (CORCON), as listed below:

- Fractional or Integer DSP Multiply (IF)
- Signed or Unsigned DSP Multiply (US)
- Conventional or Convergent Rounding (RND)
- Automatic Saturation On/Off for ACCA (SATA)
- Automatic Saturation On/Off for ACCB (SATB)
- Automatic Saturation On/Off for Writes to Data Memory (SATDW)
- Accumulator Saturation mode Selection (ACCSAT)

A block diagram of the DSP engine is shown in Figure 3-3.

TABLE 3-1: DSP INSTRUCTIONS SUMMARY

Instruction	Algebraic Operation	ACC Write Back
`CLR`	$A = 0$	Yes
`ED`	$A = (x - y)^2$	No
`EDAC`	$A = A + (x - y)^2$	No
`MAC`	$A = A + (x * y)$	Yes
`MAC`	$A = A + x^2$	No
`MOVSAC`	No change in A	Yes
`MPY`	$A = x * y$	No
`MPY`	$A = x^2$	No
`MPY.N`	$A = - x * y$	No
`MSC`	$A = A - x * y$	Yes

4.2.5 X AND Y DATA SPACES

The core has two data spaces, X and Y. These data spaces can be considered either separate (for some DSP instructions), or as one unified linear address range (for MCU instructions). The data spaces are accessed using two Address Generation Units (AGUs) and separate data paths. This feature allows certain instructions to concurrently fetch two words from RAM, thereby enabling efficient execution of DSP algorithms, such as Finite Impulse Response (FIR) filtering and Fast Fourier Transform (FFT).

The X data space is used by all instructions and supports all addressing modes. X data space has separate read and write data buses. The X read data bus is the read data path for all instructions that view data space as combined X and Y address space. It is also the X data prefetch path for the dual operand DSP instructions (`MAC` class).

The Y data space is used in concert with the X data space by the `MAC` class of instructions (`CLR`, `ED`, `EDAC`, `MAC`, `MOVSAC`, `MPY`, `MPY.N` and `MSC`) to provide two concurrent data read paths.

Both the X and Y data spaces support Modulo Addressing mode for all instructions, subject to addressing mode restrictions. Bit-Reversed Addressing mode is only supported for writes to X data space.

All data memory writes, including in DSP instructions, view data space as combined X and Y address space. The boundary between the X and Y data spaces is device-dependent and is not user-programmable.

All Effective Addresses are 16 bits wide and point to bytes within the data space. Therefore, the data space address range is 64 Kbytes, or 32K words, though the implemented memory locations vary by device.

6.8.2 UNINITIALIZED W REGISTER RESET

Any attempt to use the Uninitialized W register as an Address Pointer will reset the device. The W register array (with the exception of W15) is cleared during all Resets and is considered uninitialized until written to.

6.8.3 SECURITY RESET

If a Program Flow Change (PFC) or Vector Flow Change (VFC) targets a restricted location in a protected segment (boot and secure segment), that operation will cause a Security Reset.

The PFC occurs when the Program Counter is reloaded as a result of a call, jump, computed jump, return, return from subroutine or other form of branch instruction.

The VFC occurs when the Program Counter is reloaded with an interrupt or trap vector.

Refer to **Section 21.8 "Code Protection and CodeGuard™ Security"** for more information on Security Reset.

6.9 Using the RCON Status Bits

The user application can read the Reset Control (RCON) register after any device Reset to determine the cause of the Reset.

Note: The status bits in the RCON register should be cleared after they are read so that the next RCON register value after a device Reset will be meaningful.

Table 6-3 provides a summary of the Reset flag bit operation.

TABLE 6-3: RESET FLAG BIT OPERATION

Flag Bit	Set by:	Cleared by:
TRAPR (RCON<15>)	Trap conflict event	POR, BOR
IOPWR (RCON<14>)	Illegal opcode or Uninitialized W register access or Security Reset	POR, BOR
CM (RCON<9>)	Configuration Mismatch	POR, BOR
EXTR (RCON<7>)	$\overline{\text{MCLR}}$ Reset	POR
SWR (RCON<6>)	`RESET` instruction	POR, BOR
WDTO (RCON<4>)	WDT time-out	`PWRSAV` instruction, `CLRWDT` instruction, POR, BOR
SLEEP (RCON<3>)	`PWRSAV #SLEEP` instruction	POR, BOR
IDLE (RCON<2>)	`PWRSAV #IDLE` instruction	POR, BOR
BOR (RCON<1>)	POR, BOR	—
POR (RCON<0>)	POR	—

Note: All Reset flag bits can be set or cleared by user software.

REGISTER 7-35: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	ILR3	ILR2	ILR1	ILR0
bit 15							bit 8

U-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
—	VECNUM6	VECNUM5	VECNUM4	VECNUM3	VECNUM2	VECNUM1	VECNUM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘`0`’

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits

`1111` = CPU Interrupt Priority Level is 15
•
•
•
`0001` = CPU Interrupt Priority Level is 1
`0000` = CPU Interrupt Priority Level is 0

bit 7 **Unimplemented:** Read as ‘`0`’

bit 6-0 **VECNUM<6:0>:** Vector Number of Pending Interrupt bits

`0111111` = Interrupt vector pending is Number 135
•
•
•
`0000001` = Interrupt vector pending is Number 9
`0000000` = Interrupt vector pending is Number 8

REGISTER 8-6: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROON	—	ROSSLP	ROSEL	RODIV3[1]	RODIV2[1]	RODIV1[1]	RODIV0[1]
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ROON:** Reference Oscillator Output Enable bit
1 = Reference oscillator output is enabled on the REFCLK0 pin[2]
0 = Reference oscillator output is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **ROSSLP:** Reference Oscillator Run in Sleep bit
1 = Reference oscillator output continues to run in Sleep
0 = Reference oscillator output is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Oscillator crystal is used as the reference clock
0 = System clock is used as the reference clock

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divider bits[1]
1111 = Reference clock divided by 32,768
1110 = Reference clock divided by 16,384
1101 = Reference clock divided by 8,192
1100 = Reference clock divided by 4,096
1011 = Reference clock divided by 2,048
1010 = Reference clock divided by 1,024
1001 = Reference clock divided by 512
1000 = Reference clock divided by 256
0111 = Reference clock divided by 128
0110 = Reference clock divided by 64
0101 = Reference clock divided by 32
0100 = Reference clock divided by 16
0011 = Reference clock divided by 8
0010 = Reference clock divided by 4
0001 = Reference clock divided by 2
0000 = Reference clock

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: The reference oscillator output must be disabled (ROON = 0) before writing to these bits.
2: This pin is remappable. Refer to **Section 10.6 “Peripheral Pin Select”** for more information.

REGISTER 9-3: PMD3: PERIPHERAL MODULE DISABLE CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	R/W-0	U-0	U-0
—	—	—	—	—	CMPMD	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11	**Unimplemented:** Read as ‘0’
bit 10	**CMPMD**: Analog Comparator Module Disable bit 1 = Analog comparator module is disabled 0 = Analog comparator module is enabled
bit 9-0	**Unimplemented:** Read as ‘0’

REGISTER 9-4: PMD4: PERIPHERAL MODULE DISABLE CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	U-0	U-0	U-0
—	—	—	—	REFOMD	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4	**Unimplemented:** Read as ‘0’
bit 3	**REFOMD**: Reference Clock Generator Module Disable bit 1 = Reference clock generator module is disabled 0 = Reference clock generator module is enabled
bit 2-0	**Unimplemented:** Read as ‘0’

REGISTER 10-3: RPINR3: PERIPHERAL PIN SELECT INPUT REGISTER 3

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	T3CKR5	T3CKR4	T3CKR3	T3CKR2	T3CKR1	T3CKR0
bit 15							bit 8

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	T2CKR5	T2CKR4	T2CKR3	T2CKR2	T2CKR1	T2CKR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘`0`’

bit 13-8 **T3CKR<5:0>:** Assign Timer3 External Clock (T3CK) to the Corresponding RPn Pin bits

`111111` = Input tied to Vss
`100011` = Input tied to RP35
`100010` = Input tied to RP34
`100001` = Input tied to RP33
`100000` = Input tied to RP32
•
•
•
`00000` = Input tied to RP0

bit 7-6 **Unimplemented:** Read as ‘`0`’

bit 5-0 **T2CKR<5:0>:** Assign Timer2 External Clock (T2CK) to the Corresponding RPn Pin bits

`111111` = Input tied to Vss
`100011` = Input tied to RP35
`100010` = Input tied to RP34
`100001` = Input tied to RP33
`100000` = Input tied to RP32
•
•
•
`00000` = Input tied to RP0

REGISTER 10-10: RPINR30: PERIPHERAL PIN SELECT INPUT REGISTER 30

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	FLT3R5	FLT3R4	FLT3R3	FLT3R2	FLT3R1	FLT3R0
bit 15							bit 8

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	FLT2R5	FLT2R4	FLT2R3	FLT2R2	FLT2R1	FLT2R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘`0`’

bit 13-8 **FLT3R<5:0>:** Assign PWM Fault Input 3 (FLT3) to the Corresponding RPn Pin bits

`111111` = Input tied to VSS
`100011` = Input tied to RP35
`100010` = Input tied to RP34
`100001` = Input tied to RP33
`100000` = Input tied to RP32
•
•
•
`00000` = Input tied to RP0

bit 7-6 **Unimplemented:** Read as ‘`0`’

bit 5-0 **FLT2R<5:0>:** Assign PWM Fault Input 2 (FLT2) to the Corresponding RPn Pin bits

`111111` = Input tied to VSS
`100011` = Input tied to RP35
`100010` = Input tied to RP34
`100001` = Input tied to RP33
`100000` = Input tied to RP32
•
•
•
`00000` = Input tied to RP0

REGISTER 10-13: RPINR33: PERIPHERAL PIN SELECT INPUT REGISTER 33

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	SYNCI1R5	SYNCI1R4	SYNCI1R3	SYNCI1R2	SYNCI1R1	SYNCI1R0
bit 15							bit 8

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	FLT8R5	FLT8R4	FLT8R3	FLT8R2	FLT8R1	FLT8R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14	**Unimplemented:** Read as ‘`0`’
bit 13-8	**SYNCI1R<5:0>:** Assign PWM Master Time Base External Synchronization Signal to the Corresponding RPn Pin bits `111111` = Input tied to Vss `100011` = Input tied to RP35 `100010` = Input tied to RP34 `100001` = Input tied to RP33 `100000` = Input tied to RP32 • • • `00000` = Input tied to RP0
bit 7-6	**Unimplemented:** Read as ‘`0`’
bit 5-0	**FLT8R<5:0>:** Assign PWM Fault Input 8 (FLT8) to the Corresponding RPn Pin bits `111111` = Input tied to Vss `100011` = Input tied to RP35 `100010` = Input tied to RP34 `100001` = Input tied to RP33 `100000` = Input tied to RP32 • • • `00000` = Input tied to RP0

REGISTER 16-2: SPIxCON1: SPIx CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE[1]
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEN[3]	CKP	MSTEN	SPRE2[2]	SPRE1[2]	SPRE0[2]	PPRE1[2]	PPRE0[2]
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **DISSCK:** Disable SCKx Pin bit (SPI Master modes only)
1 = Internal SPI clock is disabled; pin functions as I/O
0 = Internal SPI clock is enabled

bit 11 **DISSDO:** Disable SDOx Pin bit
1 = SDOx pin is not used by module; pin functions as I/O
0 = SDOx pin is controlled by the module

bit 10 **MODE16:** Word/Byte Communication Select bit
1 = Communication is word-wide (16 bits)
0 = Communication is byte-wide (8 bits)

bit 9 **SMP:** SPIx Data Input Sample Phase bit
Master mode:
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
Slave mode:
SMP must be cleared when SPIx is used in Slave mode.

bit 8 **CKE:** SPIx Clock Edge Select bit[1]
1 = Serial output data changes on transition from active clock state to Idle clock state (see bit 6)
0 = Serial output data changes on transition from Idle clock state to active clock state (see bit 6)

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)[3]
1 = $\overline{\text{SSx}}$ pin is used for Slave mode
0 = $\overline{\text{SSx}}$ pin is not used by module; pin controlled by port function

bit 6 **CKP:** Clock Polarity Select bit
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

Note 1: The CKE bit is not used in the Framed SPI modes. Program this bit to ‘0’ for the Framed SPI modes (FRMEN = 1).
2: Do not set both primary and secondary prescalers to a value of 1:1.
3: This bit must be cleared when FRMEN = 1.

NOTES:

21.4 Watchdog Timer (WDT)

For the dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

21.4.1 PRESCALER/POSTSCALER

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a nominal WDT time-out period (T_{WDT}) of 1 ms in 5-bit mode, or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>) which allow the selection of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSC<2:0> bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a `PWRSAV` instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a `CLRWDT` instruction during normal execution

Note: The `CLRWDT` and `PWRSAV` instructions clear the prescaler and postscaler counts when executed.

21.4.2 SLEEP AND IDLE MODES

If the WDT is enabled, it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake the device and code execution will continue from where the `PWRSAV` instruction was executed. The corresponding SLEEP bit (RCON<3>) or IDLE bit (RCON<2>) will need to be cleared in software after the device wakes up.

21.4.3 ENABLING WDT

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to ‘`0`’. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user application to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

Note: If the WINDIS bit (FWDT<6>) is cleared, the `CLRWDT` instruction should be executed by the application software only during the last 1/4 of the WDT period. This `CLRWDT` window can be determined by using a timer. If a `CLRWDT` instruction is executed before this window, a WDT Reset occurs.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

FIGURE 21-2: WDT BLOCK DIAGRAM

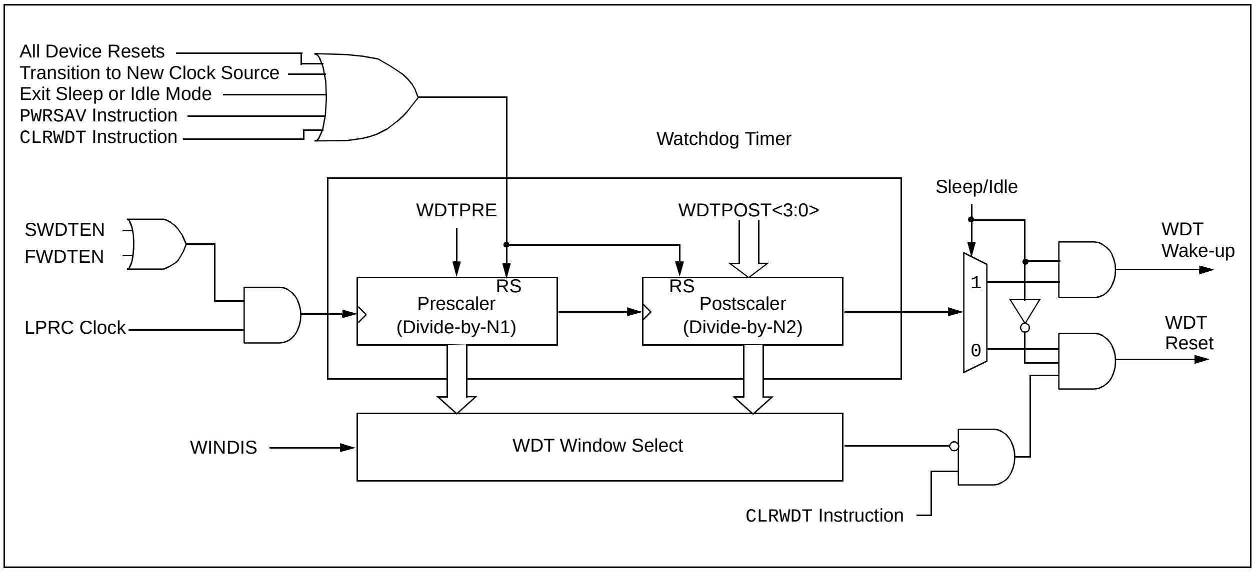


TABLE 24-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ[1]**	**Max**	**Units**	**Conditions**
	V_{IL}	**Input Low Voltage**					
DI10		I/O Pins	V_{SS}	—	0.2 V_{DD}	V	
DI15		$\overline{MCLR}$	V_{SS}	—	0.2 V_{DD}	V	
DI16		I/O Pins with OSC1	V_{SS}	—	0.2 V_{DD}	V	
DI18		I/O Pins with SDAx, SCLx	V_{SS}	—	0.3 V_{DD}	V	SMBus disabled
DI19		I/O Pins with SDAx, SCLx	V_{SS}	—	0.8	V	SMBus enabled
	V_{IH}	**Input High Voltage**					
DI20		I/O Pins Not 5V Tolerant[4]	0.7 V_{DD}	—	V_{DD}	V	
DI21		I/O Pins 5V Tolerant[4]	0.7 V_{DD}	—	5.5	V	
DI28		SDA1, SCL1	0.7 V_{DD}	—	5.5	V	SMBus disabled
DI29		SDA1, SCL1	2.1	—	5.5	V	SMBus enabled
	I_{CNPU}	**CNx Pull-up Current**					
DI30			—	250	—	μA	V_{DD} = 3.3V, V_{PIN} = V_{SS}
	I_{IL}	**Input Leakage Current[2,3,4]**					
DI50		I/O Pins with:					
		4x Driver Pins - RA0-RA2, RB0-RB2, RB5-RB10, RB15, RC1, RC2, RC9, RC10	—	—	±2	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}, Pin at high-impedance
		8x Driver Pins - RC0, RC3-RC8, RC11-RC13	—	—	±4	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}, Pin at high-impedance
		16x Driver Pins - RA3, RA4, RB3, RB4, RB11-RB14	—	—	±8	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}, Pin at high-impedance
DI55		$\overline{MCLR}$	—	—	±2	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}
DI56		OSC1	—	—	±2	μA	V_{SS} ≤ V_{PIN} ≤ V_{DD}, XT and HS modes

Note 1: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See **“Pin Diagrams”** for the list of 5V tolerant I/O pins.

5: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

6: Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 24-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ[1]**	**Max**	**Units**	**Conditions**
DI60a	I_{ICL}	**Input Low Injection Current**	0	—	-5[5,8]	mA	All pins except V_{DD}, V_{SS}, AV_{DD}, AV_{SS}, $\overline{MCLR}$, V_{CAP} and RB5
DI60b	I_{ICH}	**Input High Injection Current**	0	—	+5[6,7,8]	mA	All pins except V_{DD}, V_{SS}, AV_{DD}, AV_{SS}, $\overline{MCLR}$, V_{CAP}, RB5 and digital 5V-tolerant designated pins
DI60c	$\sum I_{ICT}$	**Total Input Injection Current (sum of all I/O and control pins)**	-20[9]	—	+20[9]	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins $(\| I_{ICL} + \| I_{ICH} \|) \le \sum I_{ICT}$

Note 1: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See **“Pin Diagrams”** for the list of 5V tolerant I/O pins.

5: V_{IL} source < (V_{SS} – 0.3). Characterized but not tested.

6: Non-5V tolerant pins V_{IH} source > (V_{DD} + 0.3), 5V tolerant pins V_{IH} source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any “positive” input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the mathematical “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 24-8: OCx/PWMx MODULE TIMING CHARACTERISTICS

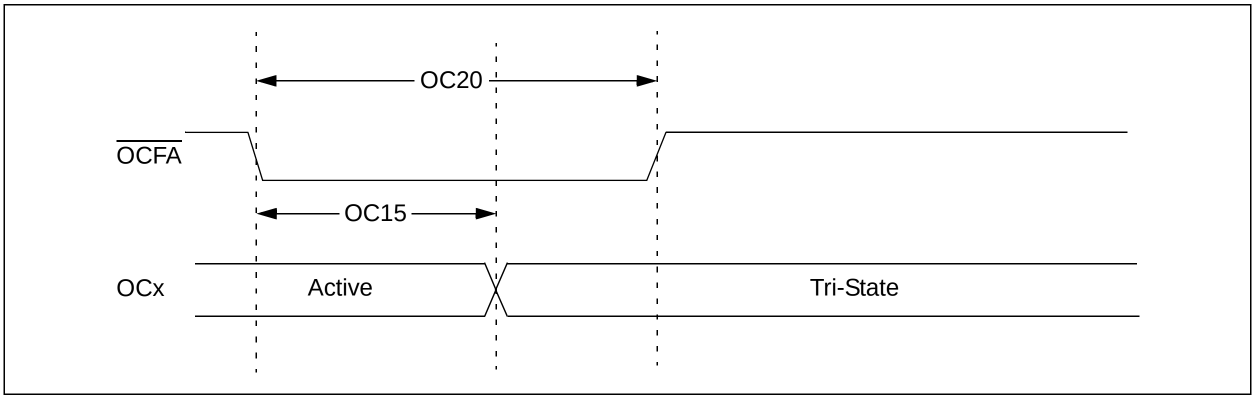


TABLE 24-28: SIMPLE OCx/PWMx MODE TIMING REQUIREMENTS

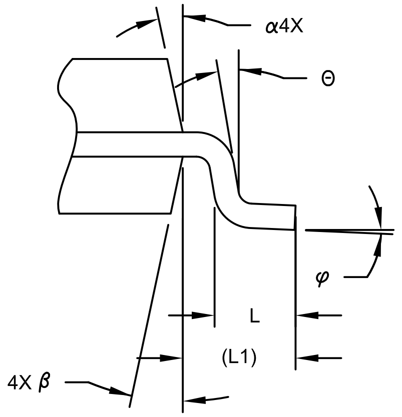
AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWMx I/O Change	—	—	TCY + 20	ns	
OC20	TFLT	Fault Input Pulse Width	TCY + 20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

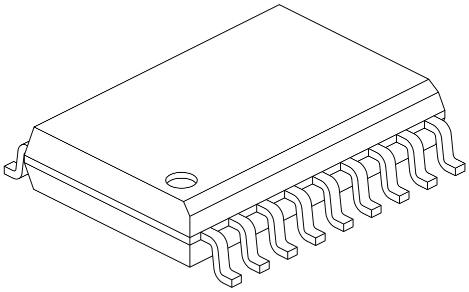
NOTES:

18-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	18		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	11.55 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

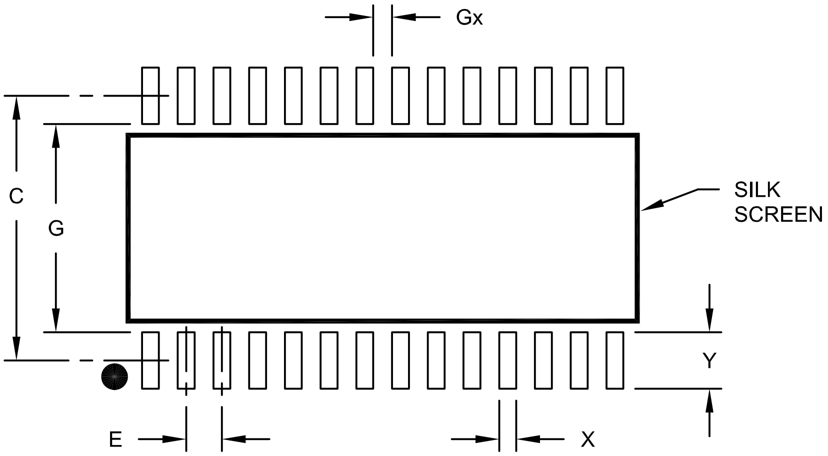
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-051C Sheet 2 of 2

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

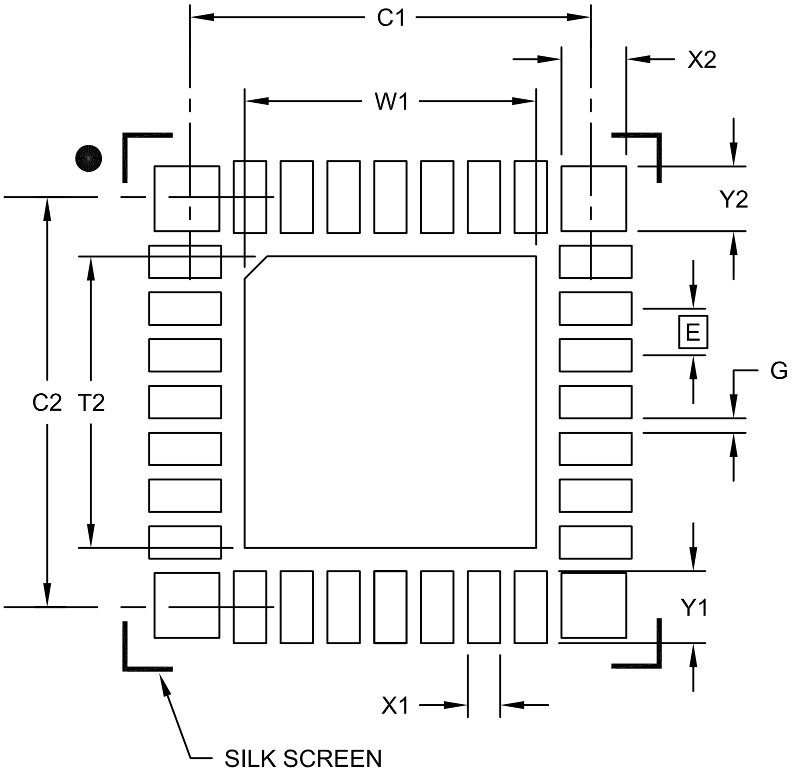
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

28-Lead Plastic Quad Flat, No Lead Package (MX) - 6x6 mm Body [UQFN] With 0.60mm Contact Length And Corner Anchors

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W1			4.05
Optional Center Pad Length	T2			4.05
Contact Pad Spacing	C1		5.70	
Contact Pad Spacing	C2		5.70	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.00
Corner Pad Width (X4)	X2			0.90
Corner Pad Length (X4)	Y2			0.90
Distance Between Pads	G	0.20		

Notes:

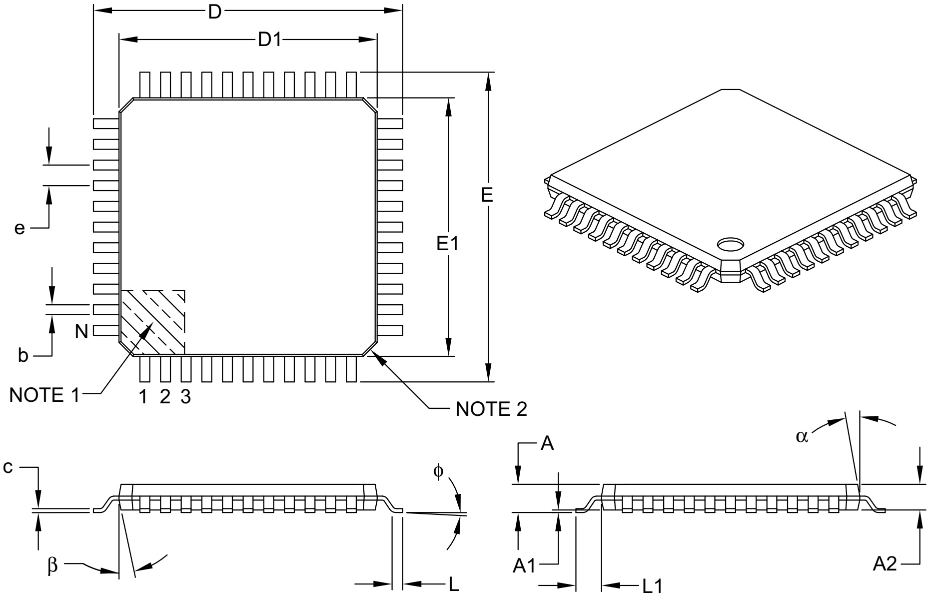
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2209B

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	44		
Lead Pitch	e	0.80 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B